



自主封測 品質把控 售後保障

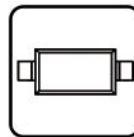
WEB | WWW.TDSEMIC.COM



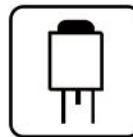
電源管理



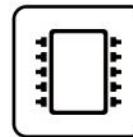
顯示驅動



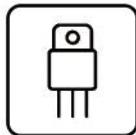
二三極管



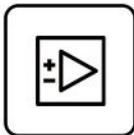
LDO穩壓器



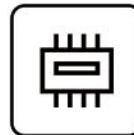
觸摸芯片



MOS管



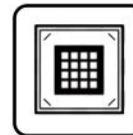
運算放大器



存儲芯片



MCU



串口通信

K310-TD

產品規格說明書

Surface Mount Schottky Barrier Rectifier
 Reverse Voltage - 20 to 200 V
 Forward Current - 3.0A

FEATURES

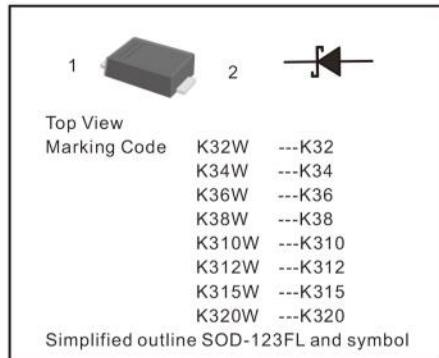
- Metal silicon junction, majority carrier conduction
- For surface mounted applications
- Low power loss, high efficiency
- High forward surge current capability
- For use in low voltage, high frequency inverters, free wheeling, and polarity protection applications

MECHANICAL DATA

- Case: SOD-123FL
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 15mg 0.00048oz

PINNING

PIN	DESCRIPTION
1	Cathode
2	Anode



Absolute Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified. Single phase, half wave, 60Hz resistive or inductive load, for capacitive load, derate by 20 %

Parameter	Symbols	K32W	K34W	K36W	K38W	K310W	K312	K315W	K320W	Units		
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	20	40	60	80	100	120	150	200	V		
Maximum RMS voltage	V_{RMS}	14	28	42	56	70	84	105	140	V		
Maximum DC Blocking Voltage	V_{DC}	20	40	60	80	100	120	150	200	V		
Maximum Average Forward Rectified Current	$I_{F(AV)}$	3.0							A			
Peak Forward Surge Current, 8.3ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	I_{FSM}	80							A			
Max Instantaneous Forward Voltage at 3A	V_F	0.55		0.70		0.85		0.95		V		
Maximum DC Reverse Current $T_a = 25^\circ C$ at Rated DC Reverse Voltage $T_a = 100^\circ C$	I_R	0.5 10		0.3 5						mA		
Typical Junction Capacitance ⁽¹⁾	C_j	250		160						pF		
Typical Thermal Resistance ⁽²⁾	$R_{\theta JA}$	80							°C/W			
Operating Junction Temperature Range	T_j	-55 ~ +125							°C			
Storage Temperature Range	T_{stg}	-55 ~ +150							°C			

(1) Measured at 1 MHz and applied reverse voltage of 4 V D.C.

(2) P.C.B. mounted with 2.0" X 2.0" (5 X 5 cm) copper pad areas.

Fig.1 Forward Current Derating Curve

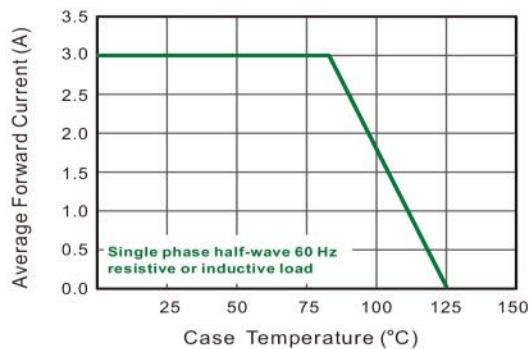


Fig.2 Typical Reverse Characteristics

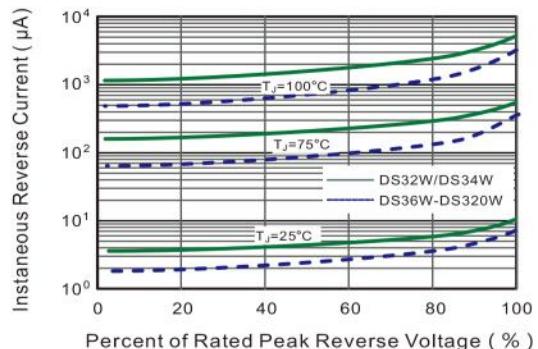


Fig.3 Typical Forward Characteristic

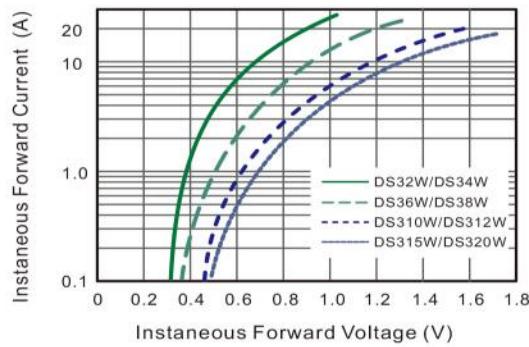


Fig.4 Typical Junction Capacitance

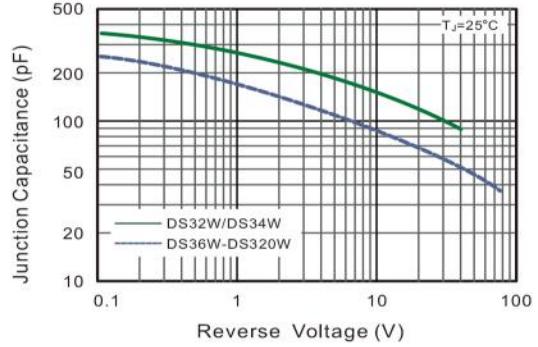


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current

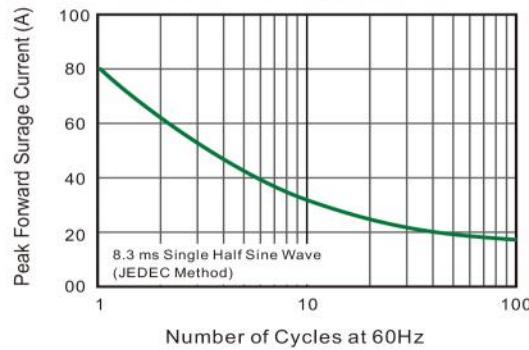
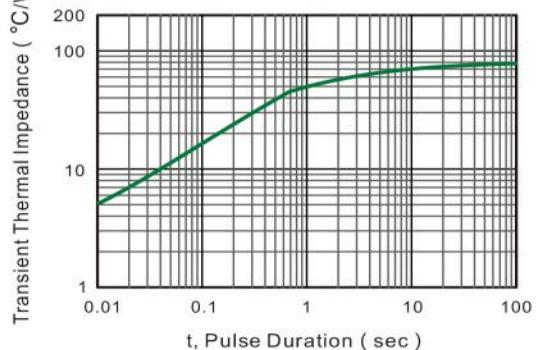


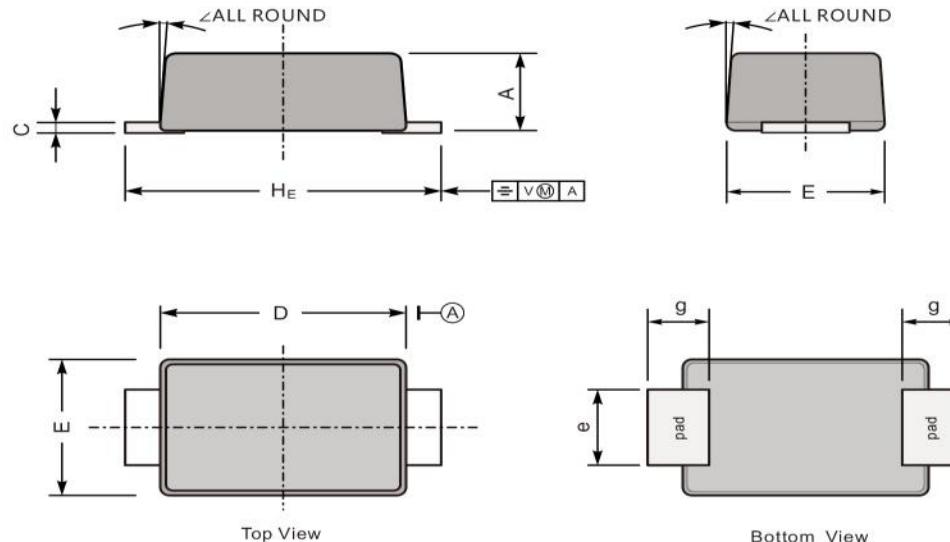
Fig.6- Typical Transient Thermal Impedance



PACKAGE OUTLINE

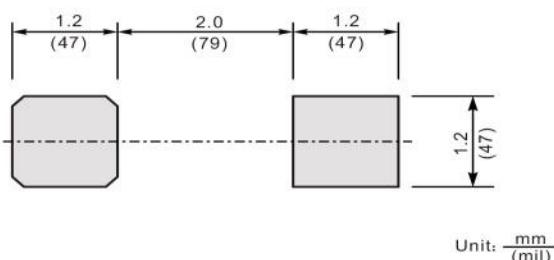
Plastic surface mounted package; 2 leads

SOD-123FL



UNIT		A	C	D	E	e	g	H _E	α
mm	max	1.1	0.20	2.9	1.9	1.1	0.9	3.8	7°
	min	0.9	0.12	2.6	1.7	0.8	0.7	3.5	
mil	max	43	7.9	114	75	43	35	150	7°
	min	35	4.7	102	67	31	28	138	

The recommended mounting pad size



Marking

Type number	Marking code
K32W	K32
K34W	K34
K36W	K36
K38W	K38
K310W	K310
K312W	K312
K315W	K315
K320W	K320